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PRESS RELEASE

Contact Information:

Kimberly Sterling, IPC Vice President, Marketing and Communications

P: 847-790-5305. After Sept 17, 847-509-9700.

E: KimSterling@ipc.org

For Immediate Release

IPC Releases Revised Key Printed Circuit Board Qualification and Acceptability Standards

NORTHBROOK, Ill., September 1, 2004 - IPC-Association Connecting Electronics IndustriesR announced today the release of IPC-A-600G, Acceptability of Printed Boards, and IPC-6012B, Qualification and Performance Specification for Rigid Printed Boards.

The documents represent the culmination of four years of revision activity and the contribution of dozens of industry volunteers. Together, the two documents represent the core IPC documents for describing the acceptable and nonconforming conditions that are either externally or internally visible on finished printed circuit boards(PCBs) and the frequency of end-product inspections.

Main office Europe:
PIEK International
Education Centre (I.E.C.) B.V.
Schelsberg 111-113
6413 AC HEERLEN
The Netherlands

E-Mail: info@piekiec.com
<http://www.piekiec.com>

VAT: NL-8006.68.492.B.01

Phone: +31 45 570 33 33
Fax: +31 45 570 33 20

Chamber of Commerce
South Limburg: 14038721

Banking
Postbank
Acc.: 2032248
ABN - AMRO Heerlen
Acc.: 47.60.96.189



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The documents were revised simultaneously, underscoring their close relationship. IPC-A-600 relies on IPC-6012 for the minimum acceptability requirements for PCBs and the acceptance testing frequencies required for PCB manufacture and procurement. IPC-6012 relies on IPC-A-600 for visual support and interpretation of those requirements.

Revision G of IPC-A-600 incorporates over 80 new or revised graphics and photographs. Existing sections such as those for measles, dewetting, conductor width, etchback, foil cracks, and flexible circuits have been updated. New sections have also been created to address surface plating requirements, smear removal, wire bond pads and lifted lands prior to thermal stress.

IPC-6012 has changed significantly as well. Advances in surface finishes and hole densities and issues involving BGA, wire bond pads and internal annular ring requirements have all been addressed. A major addition to the document includes a performance specification "slash" sheet for the aerospace and military avionics segment of the industry which provides common exceptions to existing IPC-6012 Class 3 performance attributes.

Don Dupriest, Lockheed Martin Missiles and Fire Control, chair of the IPC-D-30 Rigid Printed Board Committee, commented: "The release of these documents represents an aggressive attempt to stay current with performance requirements of present technology, including high density interconnect. With the contributions of so many individuals, the documents truly represent an industry consensus that PCB manufacturers and end customers should be pleased with."

Both documents are available in hard copy or electronic format and take advantage of IPC's new lower prices on single-user electronic formats.

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